

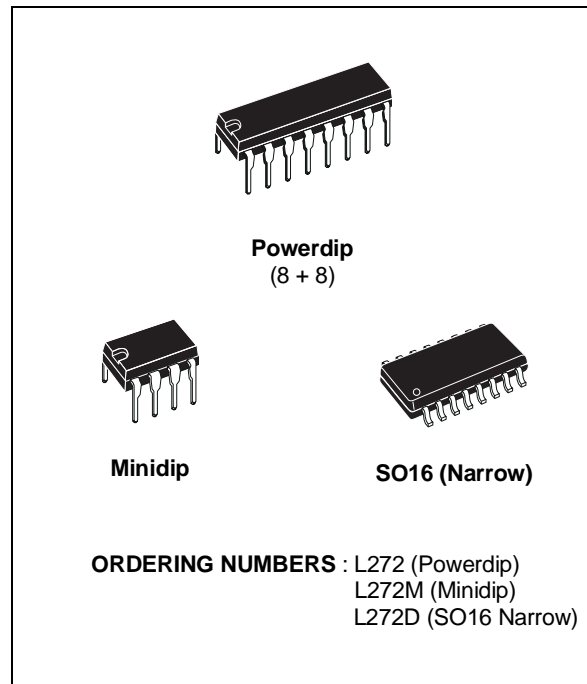
**DUAL POWER OPERATIONAL AMPLIFIERS**

- OUTPUT CURRENT TO 1 A
- OPERATES AT LOW VOLTAGES
- SINGLE OR SPLIT SUPPLY
- LARGE COMMON-MODE AND DIFFERENTIAL MODE RANGE
- GROUND COMPATIBLE INPUTS
- LOW SATURATION VOLTAGE
- THERMAL SHUTDOWN

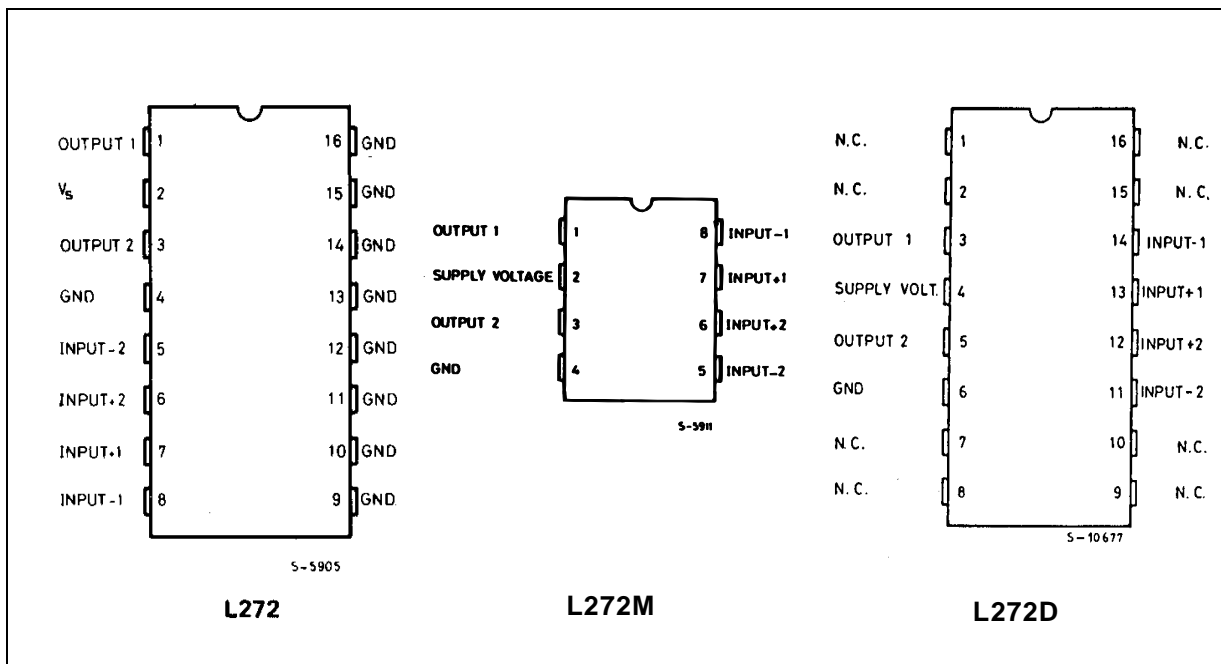
**DESCRIPTION**

The L272 is a monolithic integrated circuits in Powerdip, Minidip and SO packages intended for use as power operational amplifiers in a wide range of applications including servo amplifiers and power supplies, compact disc, VCR, etc.

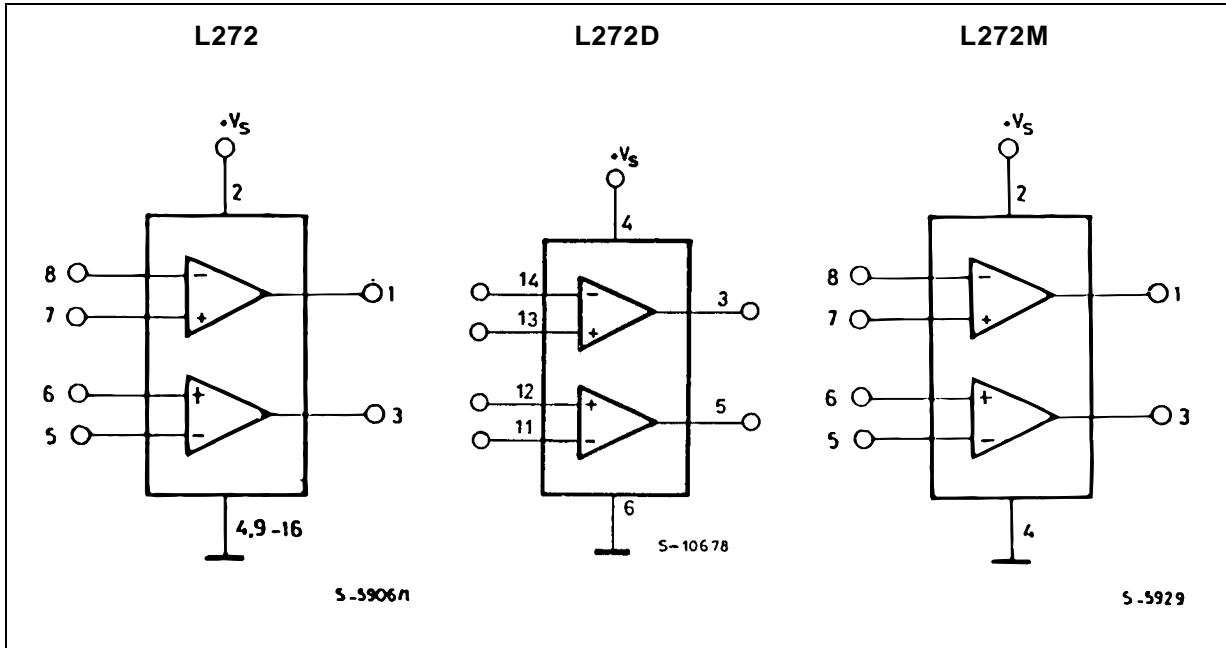
The high gain and high output power capability provide superior performance whatever an operational amplifier/power booster combination is required.



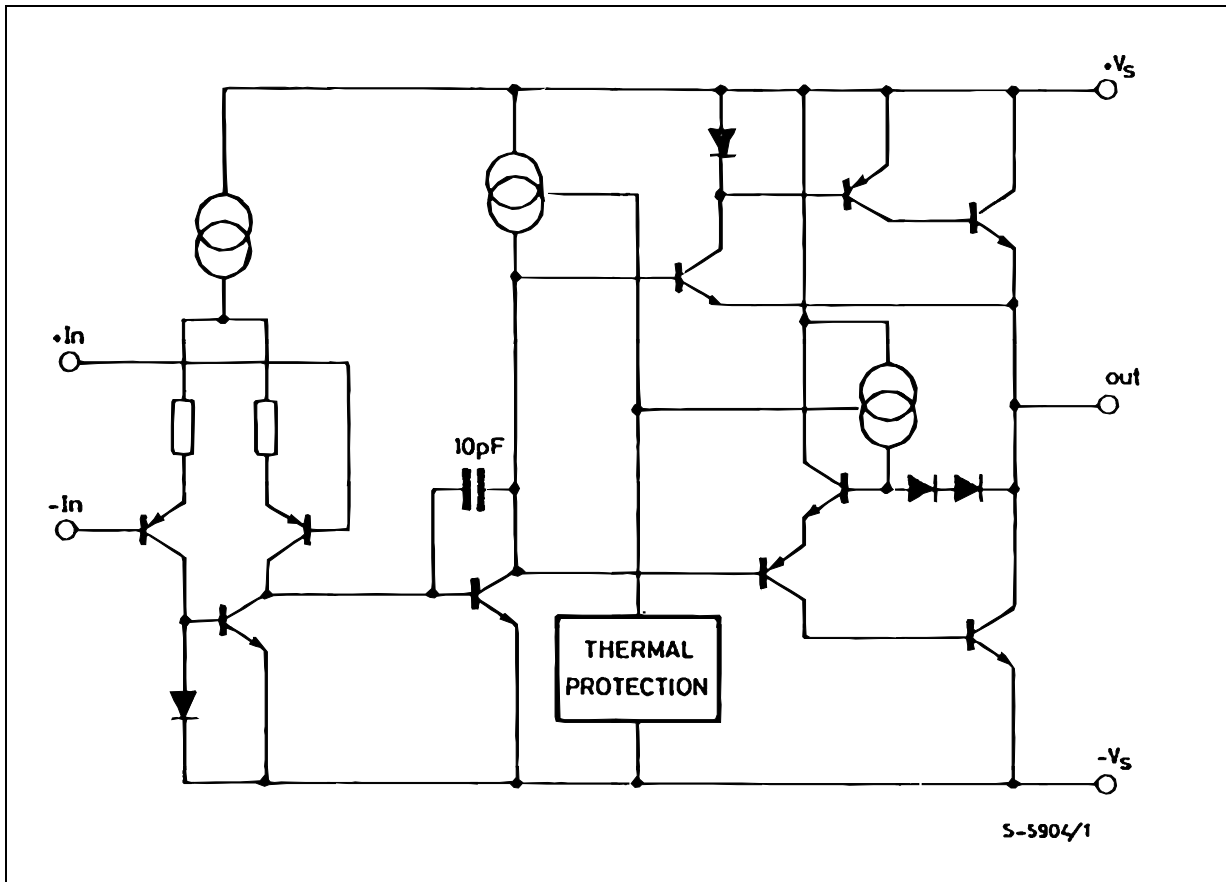
**PIN CONNECTIONS (top view)**



BLOCK DIAGRAMS



SCHEMATIC DIAGRAM (one only)



## ABSOLUTE MAXIMUM RATINGS

| Symbol                            | Parameter   | Value            | Unit   |
|-----------------------------------|---|------------------|--------|
| V <sub>s</sub>                    | Supply Voltage  | 28               | V      |
| V <sub>i</sub>                    | Input Voltage   | V <sub>s</sub>   |        |
| V <sub>i</sub>                    | Differential Input Voltage  | ± V <sub>s</sub> |        |
| I <sub>o</sub>                    | DC Output Current   | 1                | A      |
| I <sub>p</sub>                    | Peak Output Current (non repetitive)  | 1.5              | A      |
| P <sub>tot</sub>                  | Power Dissipation at:<br>T <sub>amb</sub> = 80°C (L272), T <sub>amb</sub> = 50°C (L272M), T <sub>case</sub> = 90 °C (L272D)<br>T <sub>case</sub> = 75 °C (L272) | 1.2<br>5         | W<br>W |
| T <sub>op</sub>                   | Operating Temperature Range (L272D)   | – 40 to 85       | °C     |
| T <sub>stg</sub> , T <sub>j</sub> | Storage and Junction Temperature  | – 40 to 150      | °C     |

## THERMAL DATA

| Symbol                    | Parameter                                | Powerdip | SO16  | Minidip | Unit |
|---------------------------|--|----------|-------|---------|------|
| R <sub>th j-case</sub>    | Thermal Resistance Junction-pins Max.    | 15       | –     | * 70    | °C/W |
| R <sub>th j-amb</sub>     | Thermal Resistance Junction-ambient Max. | 70       | –     | 100     | °C/W |
| R <sub>th j-alumina</sub> | Thermal Resistance Junction-alumina Max. | –        | ** 50 | –       | °C/W |

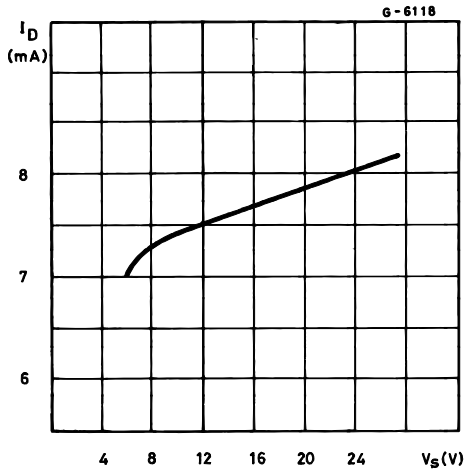
\* Thermal resistance junction-pin 4

\*\* Thermal resistance junctions-pins with the chip soldered on the middle of an alumina supporting substrate measuring 15x 20mm; 0.65mm thickness and infinite heatsink.

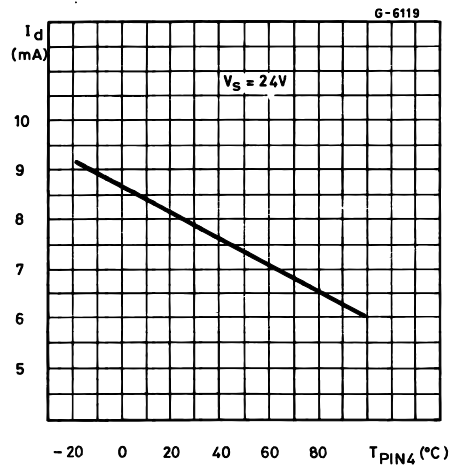
ELECTRICAL CHARACTERISTICS (V<sub>s</sub> = 24V, T<sub>amb</sub> = 25°C unless otherwise specified)

| Symbol          | Parameter                             | Test Conditions  | Min. | Typ.           | Max.     | Unit     |
|-----------------|---------------------------------------|--|------|----------------|----------|----------|
| V <sub>s</sub>  | Supply Voltage                        |  | 4    |                | 28       | V        |
| I <sub>s</sub>  | Quiescent Drain Current               | $V_O = \frac{V_S}{2}$<br>V <sub>s</sub> = 24V<br>V <sub>s</sub> = 12V  |      | 8<br>7.5       | 12<br>11 | mA<br>mA |
| I <sub>b</sub>  | Input Bias Current                    |  |      | 0.3            | 2.5      | µA       |
| V <sub>os</sub> | Input Offset Voltage                  |  |      | 15             | 60       | mV       |
| I <sub>os</sub> | Input Offset Current                  |  |      | 50             | 250      | nA       |
| SR              | Slew Rate                             |  |      | 1              |          | V/µs     |
| B               | Gain-bandwidth Product                |  |      | 350            |          | kHz      |
| R <sub>i</sub>  | Input Resistance                      |  | 500  |                |          | kΩ       |
| G <sub>v</sub>  | O. L. Voltage Gain                    | f = 100Hz<br>f = 1kHz  | 60   | 70<br>50       |          | dB<br>dB |
| e <sub>N</sub>  | Input Noise Voltage                   | B = 20kHz  |      | 10             |          | µV       |
| I <sub>N</sub>  | Input Noise Current                   | B = 20kHz  |      | 200            |          | pA       |
| CRR             | Common Mode Rejection                 | f = 1kHz   | 60   | 75             |          | dB       |
| SVR             | Supply Voltage Rejection              | f = 100Hz, R <sub>G</sub> = 10kΩ, V <sub>R</sub> = 0.5V<br>V <sub>s</sub> = 24V<br>V <sub>s</sub> = ± 12V<br>V <sub>s</sub> = ± 6V | 54   | 70<br>62<br>56 |          | dB       |
| V <sub>o</sub>  | Output Voltage Swing                  | I <sub>p</sub> = 0.1A<br>I <sub>p</sub> = 0.5A   | 21   | 23<br>22.5     |          | V<br>V   |
| C <sub>s</sub>  | Channel Separation                    | f = 1 kHz; R <sub>L</sub> = 10Ω, G <sub>v</sub> = 30dB<br>V <sub>s</sub> = 24V<br>V <sub>s</sub> = ± 6V                            |      | 60<br>60       |          | dB       |
| d               | Distortion                            | f = 1kHz, G <sub>v</sub> = 3 dB, V <sub>s</sub> = 24V, R <sub>L</sub> = ∞  |      | 0.5            |          | %        |
| T <sub>sd</sub> | Thermal Shutdown Junction Temperature |  |      | 145            |          | °C       |

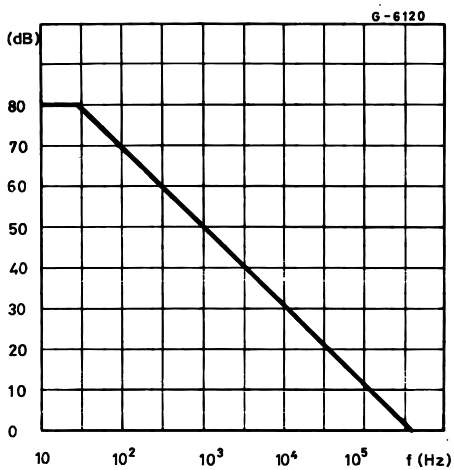
**Figure 1 :** Quiescent Current versus Supply Voltage



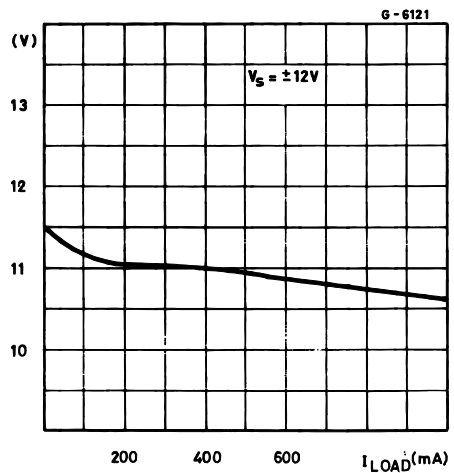
**Figure 2 :** Quiescent Drain Current versus Temperature



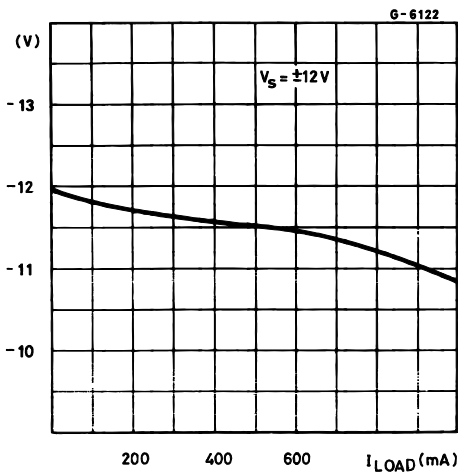
**Figure 3 :** Open Loop Voltage Gain



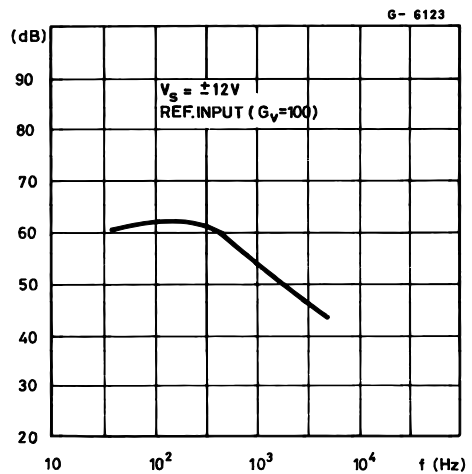
**Figure 4 :** Output Voltage Swing versus Load Current



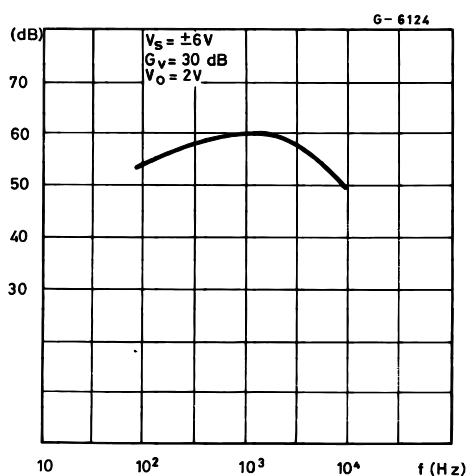
**Figure 5 :** Output Voltage Swing versus Load Current



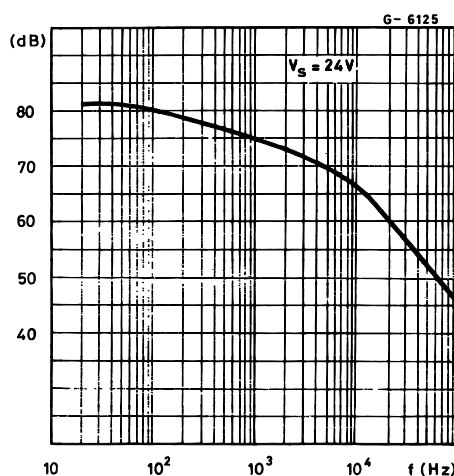
**Figure 6 :** Supply Voltage Rejection versus Frequency



**Figure 7 :** Channel Separation versus Frequency



**Figure 8 :** Common Mode Rejection versus Frequency



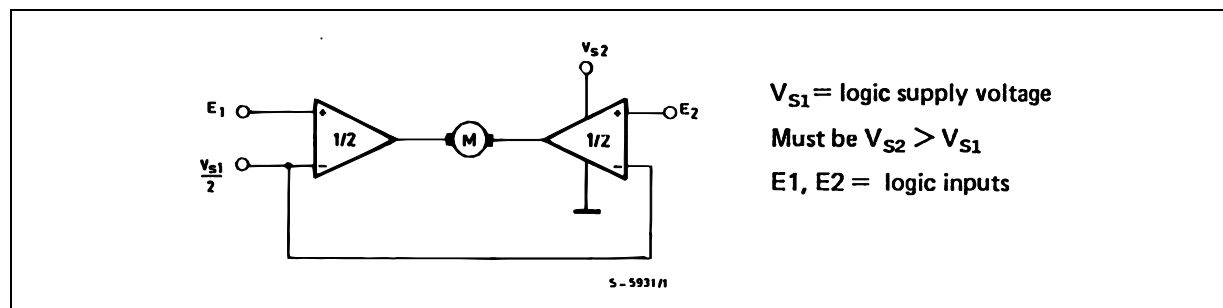
**APPLICATION SUGGESTION**

**NOTE**

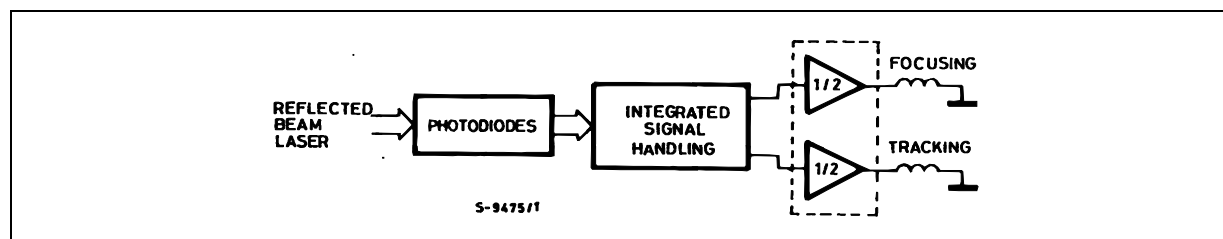
In order to avoid possible instability occurring into final stage the usual suggestions for the linear power stages are useful, as for instance :

- layout accuracy ;
- a 100nF capacitor connected between supply pins and ground ;
- boucherot cell (0.1 to 0.2  $\mu$ F + 1  $\Omega$  series) between outputs and ground or across the load.

**Figure 9 :** Bidirectional DC Motor Control with  $\mu$ P Compatible Inputs



**Figure 10 :** Servocontrol for Compact-disc



**Figure 11 :** Capstan Motor Control in Video Recorders

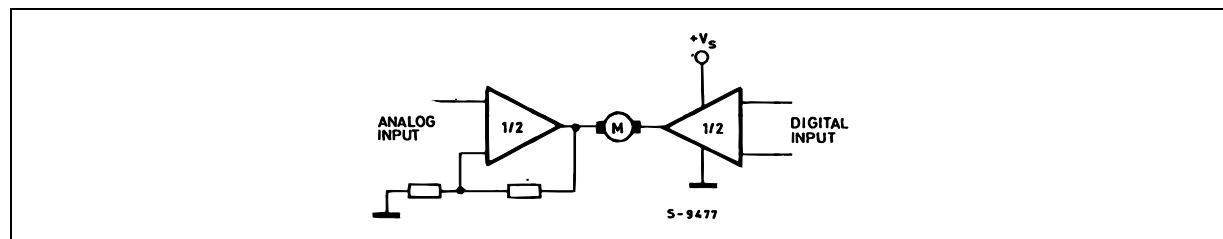
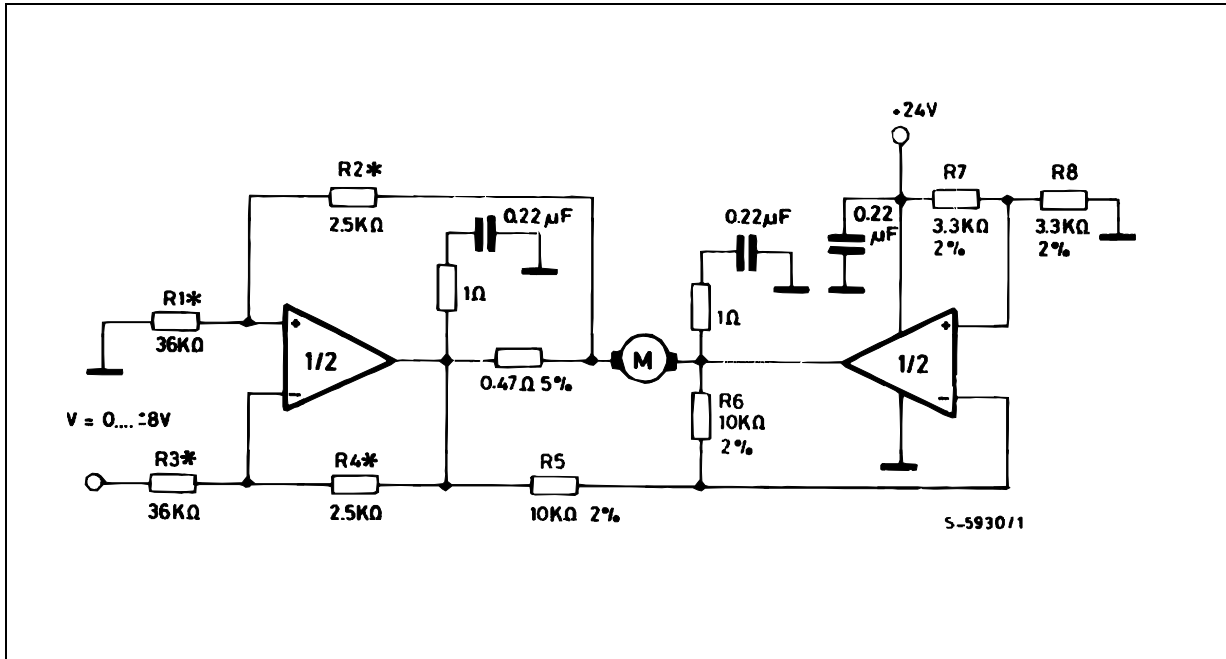


Figure 12 : Motor Current Control Circuit.

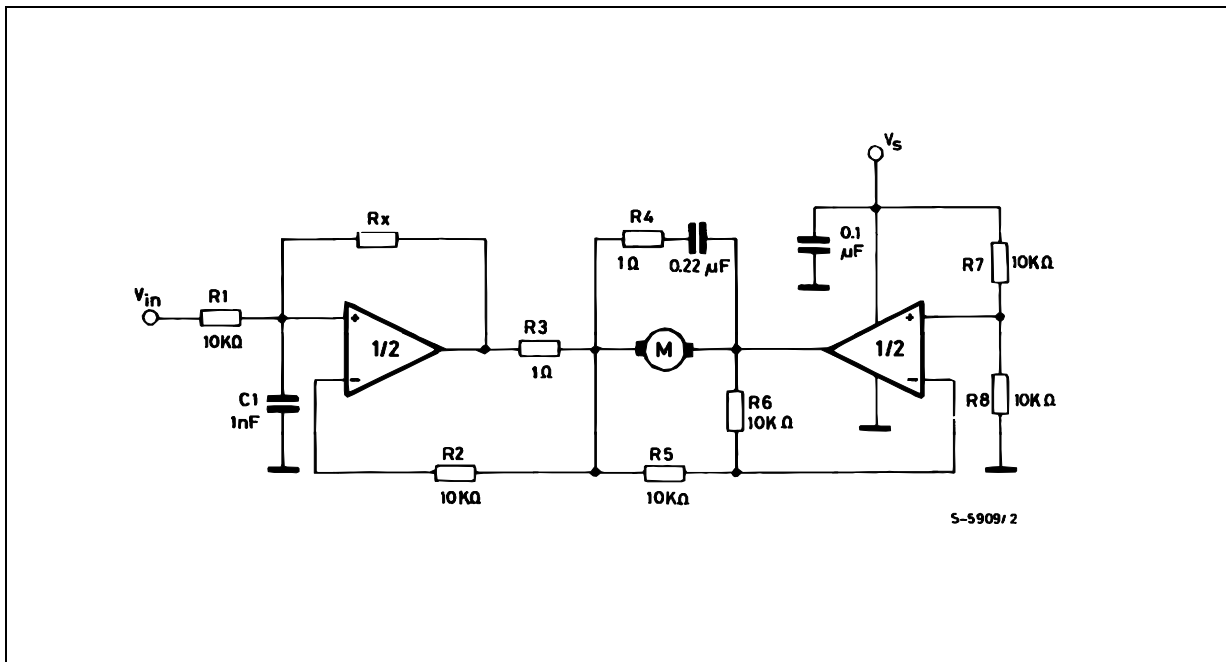


Note : The input voltage level is compatible with L291 (5-BIT D/A converter).

Figure 13 : Bidirectional Speed Control of DC Motors.

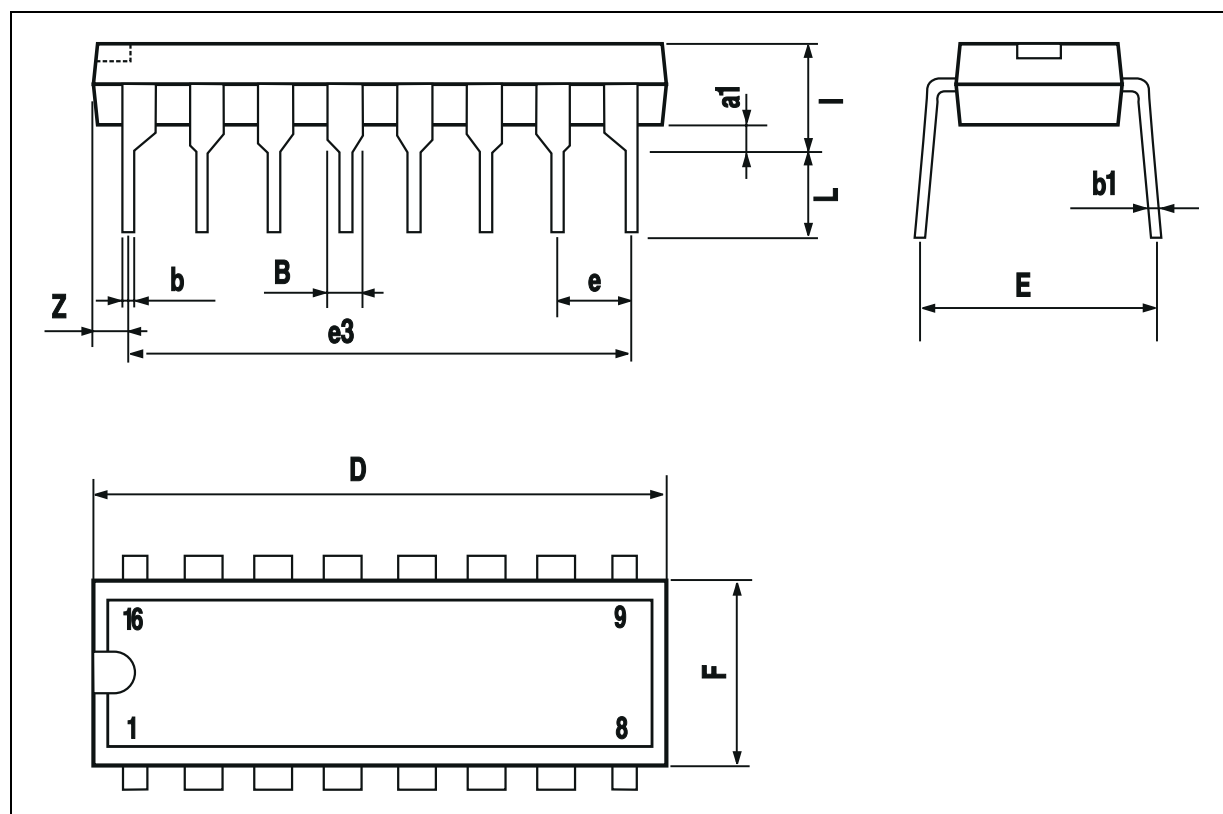
For circuit stability ensure that  $R_x > \frac{2R_3 \cdot R_1}{R_M}$  where  $R_M$  = internal resistance of motor.

The voltage available at the terminals of the motor is  $V_M = 2 \left( V_i \cdot \frac{V_s}{2} \right) + |R_o| \cdot I_M$  where  $|R_o| = \frac{2R \cdot R_1}{R_x}$  and  $I_M$  is the motor current.



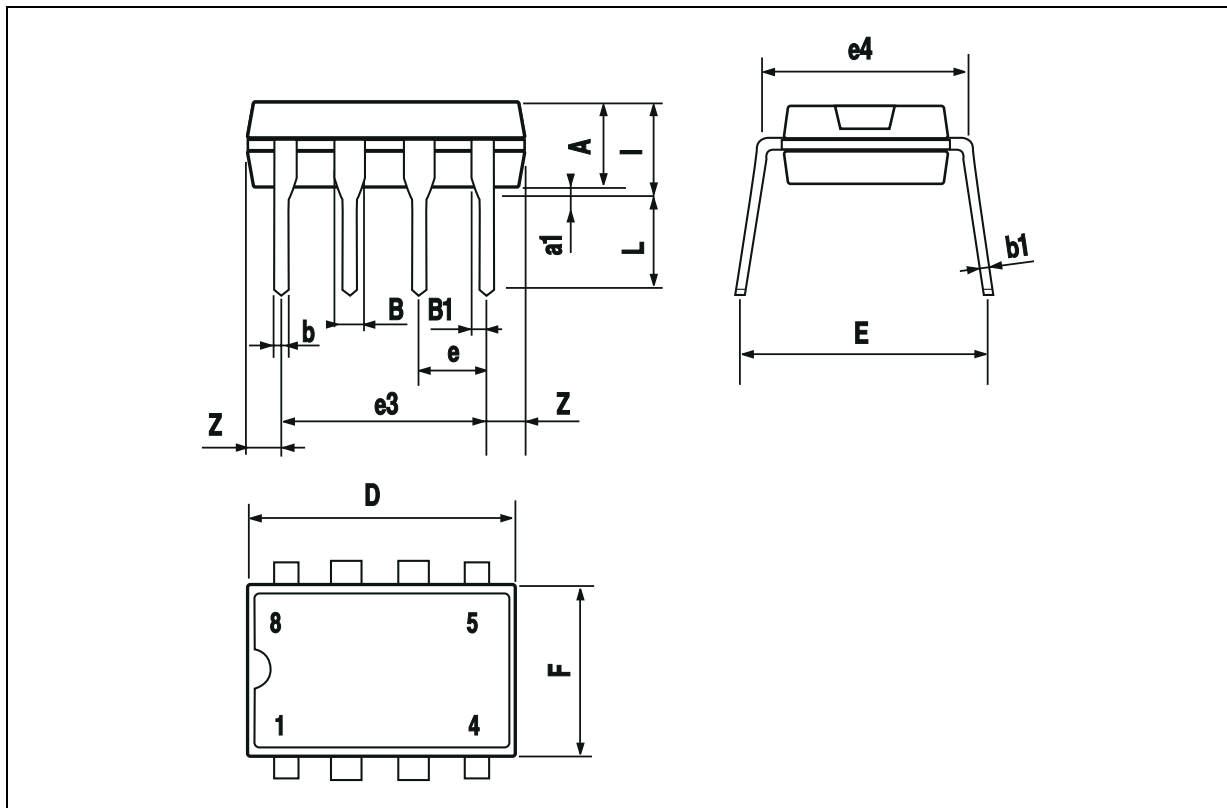
## POWERDIP 16 PACKAGE MECHANICAL DATA

| DIM. | mm   |       |      | inch  |       |       |
|------|------|-------|------|-------|-------|-------|
|      | MIN. | TYP.  | MAX. | MIN.  | TYP.  | MAX.  |
| a1   | 0.51 |       |      | 0.020 |       |       |
| B    | 0.85 |       | 1.40 | 0.033 |       | 0.055 |
| b    |      | 0.50  |      |       | 0.020 |       |
| b1   | 0.38 |       | 0.50 | 0.015 |       | 0.020 |
| D    |      |       | 20.0 |       |       | 0.787 |
| E    |      | 8.80  |      |       | 0.346 |       |
| e    |      | 2.54  |      |       | 0.100 |       |
| e3   |      | 17.78 |      |       | 0.700 |       |
| F    |      |       | 7.10 |       |       | 0.280 |
| I    |      |       | 5.10 |       |       | 0.201 |
| L    |      | 3.30  |      |       | 0.130 |       |
| Z    |      |       | 1.27 |       |       | 0.050 |



## MINIDIP PACKAGE MECHANICAL DATA

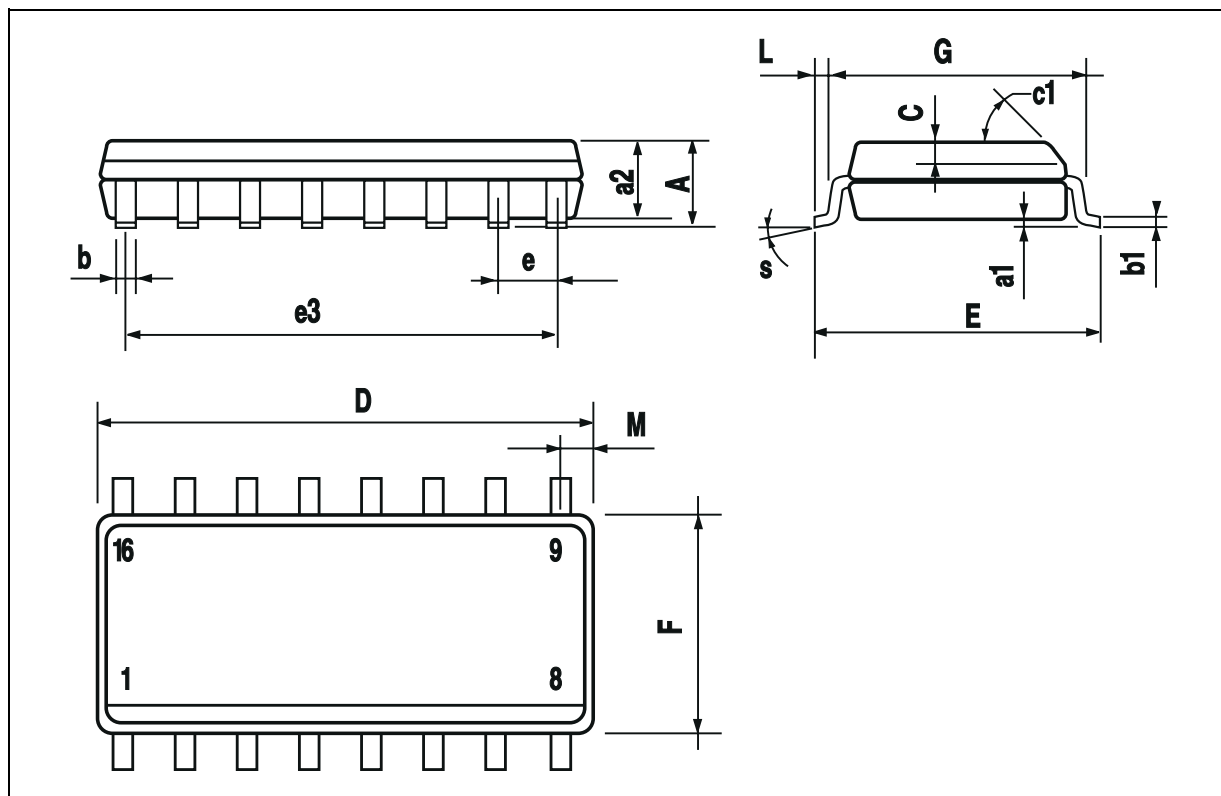
| DIM. | mm    |      |       | inch  |       |       |
|------|-------|------|-------|-------|-------|-------|
|      | MIN.  | TYP. | MAX.  | MIN.  | TYP.  | MAX.  |
| A    |       | 3.32 |       |       | 0.131 |       |
| a1   | 0.51  |      |       | 0.020 |       |       |
| B    | 1.15  |      | 1.65  | 0.045 |       | 0.065 |
| b    | 0.356 |      | 0.55  | 0.014 |       | 0.022 |
| b1   | 0.204 |      | 0.304 | 0.008 |       | 0.012 |
| D    |       |      | 10.92 |       |       | 0.430 |
| E    | 7.95  |      | 9.75  | 0.313 |       | 0.384 |
| e    |       | 2.54 |       |       | 0.100 |       |
| e3   |       | 7.62 |       |       | 0.300 |       |
| e4   |       | 7.62 |       |       | 0.300 |       |
| F    |       |      | 6.6   |       |       | 0.260 |
| I    |       |      | 5.08  |       |       | 0.200 |
| L    | 3.18  |      | 3.81  | 0.125 |       | 0.150 |
| Z    |       |      | 1.52  |       |       | 0.060 |





## SO16 NARROW PACKAGE MECHANICAL DATA

| DIM. | mm         |      |      | inch  |       |       |
|------|------------|------|------|-------|-------|-------|
|      | MIN.       | TYP. | MAX. | MIN.  | TYP.  | MAX.  |
| A    |            |      | 1.75 |       |       | 0.069 |
| a1   | 0.1        |      | 0.25 | 0.004 |       | 0.009 |
| a2   |            |      | 1.6  |       |       | 0.063 |
| b    | 0.35       |      | 0.46 | 0.014 |       | 0.018 |
| b1   | 0.19       |      | 0.25 | 0.007 |       | 0.010 |
| C    |            | 0.5  |      |       | 0.020 |       |
| c1   | 45° (typ.) |      |      |       |       |       |
| D    | 9.8        |      | 10   | 0.386 |       | 0.394 |
| E    | 5.8        |      | 6.2  | 0.228 |       | 0.244 |
| e    |            | 1.27 |      |       | 0.050 |       |
| e3   |            | 8.89 |      |       | 0.350 |       |
| F    | 3.8        |      | 4.0  | 0.150 |       | 0.157 |
| L    | 0.4        |      | 1.27 | 0.150 |       | 0.050 |
| M    |            |      | 0.62 |       |       | 0.024 |
| S    | 8° (max.)  |      |      |       |       |       |



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